

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6272735

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHE-CHENG CHANG	06/29/2015
CHIH-HAN LIN	06/29/2015
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16948039
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
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Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	20150391/24061.3453US03
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM
SIGNATURE:	/Janie Martinez-Holm/
DATE SIGNED:	08/28/2020
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, Che-Cheng CHANG and Chih-Han LIN
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as
described and set forth in the below identified application for United States Letters Patent:

Title: FIN FIELD EFFECT TRANSISTOR (FINFET) DEVICE STRUCTURE WITH STOP
LAYER AND METHOD FOR FORMING THE SAME

Filed: _____ Serial No. _____

Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No.8, Li-Hsin Road, 6,
Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as
ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application
and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and
valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have
sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said
Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to
the said invention and application and all future improvements thereon, and in and to any Letters
Patent which may hereafter be granted on the same in the United States, the said interest to be held
and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by
said Assignor had this Assignment and transfer not been made, to the full end and term of any
Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or
in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee,
but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or
applications, execute, verify, acknowledge and deliver all such further papers, including
applications for Letters Patent and for the reissue thereof, and instruments of assignment and
transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or
maintain Letters Patent for said invention and improvement, and to vest title thereto in said
Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)
indicated.

2015/6/29 _____
Date Name: Che-Cheng CHANG (Last name: CHANG)

2015/6/29 _____
Date Name: Chih-Han LIN (Last name: LIN)